

TMS320C6743
Fixed- and Floating-Point
Digital Signal Processor
Silicon Revisions 3.0, 2.1, 2.0, 1.1, and 1.0

Silicon Errata



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TMS320C6743

Silicon Revisions 3.0, 2.1, 2.0, 1.1, and 1.0

1 Introduction

This document describes the known exceptions to the functional specifications for the *TMS320C6743 Fixed/Floating-Point Digital Signal Processor* devices (for example, TMS320C6743). For more detailed information on these devices, see the device-specific data manual: *TMS320C6743 Fixed/Floating-Point Digital Signal Processor* data manual (literature number [SPRS565](#)).

For additional peripheral information, see the latest version of the *TMS320C6743 DSP Technical Reference Manual* (Literature Number: [SPRUH90](#)).

The advisory numbers in this document may not be sequential. Some advisory numbers may be moved to the next revision and others may have been removed and documented in the device-specific data manual or peripheral user's guide. When items are moved or deleted, the remaining numbers remain the same and are not resequenced.

This document also contains Usage Notes. Usage Notes highlight and describe particular situations where the device's behavior may not match presumed or documented behavior. This may include behaviors that affect device performance or functional correctness. These notes will be incorporated into future documentation updates for the device (such as the device-specific data manual), and the behaviors they describe will not be altered in future device revisions.

1.1 Device and Development Support Tool Nomenclature

To designate the stages in the product development cycle, TI assigns prefixes to the part numbers of all devices and support tools. Each commercial family member has one of three prefixes: TMX, TMP, or TMS (for example, TMS320C6743CZKB3). Texas Instruments recommends two of three possible prefix designators for its support tools: TMDX and TMDS. These prefixes represent evolutionary stages of product development from engineering prototypes (TMX/TMDX) through fully-qualified production devices/tools (TMS/TMDS).

Device development evolutionary flow:

TMX	Experimental device that is not necessarily representative of the final device's electrical specifications
TMP	Final silicon die that conforms to the device's electrical specifications but has not completed quality and reliability verification
TMS	Fully-qualified production device

Support tool development evolutionary flow:

TMDX	Development-support product that has not yet completed Texas Instruments internal qualification testing
TMDS	Fully-qualified development-support product

TMX and TMP devices and TMDX development-support tools are shipped against the following disclaimer:

"Developmental product is intended for internal evaluation purposes."

TMS devices and TMDS development-support tools have been characterized fully, and the quality and reliability of the device have been demonstrated fully. TI's standard warranty applies.

Predictions show that prototype devices (X or P) have a greater failure rate than the standard production devices. Texas Instruments recommends that these devices not be used in any production system because their expected end-use failure rate still is undefined. Only qualified production devices are to be used.

1.2 Package Symbolization and Revision Identification

[Example, Device Revision Codes for TMS320C6743 \(ZKB Package\)](#) shows an example of the TMS320C6743 processor package symbolization. The device revision code can be identified by the markings on the top of the package; for example, the "C" between the device number and the package identifier indicates the device revision code (that is, Silicon Revision 2.1) A "D" between the device number and the package identifier would indicate the device revision code for Silicon Revision 3.0.

[Table 1](#) lists the device revision codes for the TMS320C6743 processor, as well as shows the relationship between the device revision codes and silicon revisions.

For more detailed information on device nomenclature breakdowns, see the "Device and Documentation Support" section of the device-specific data manual.

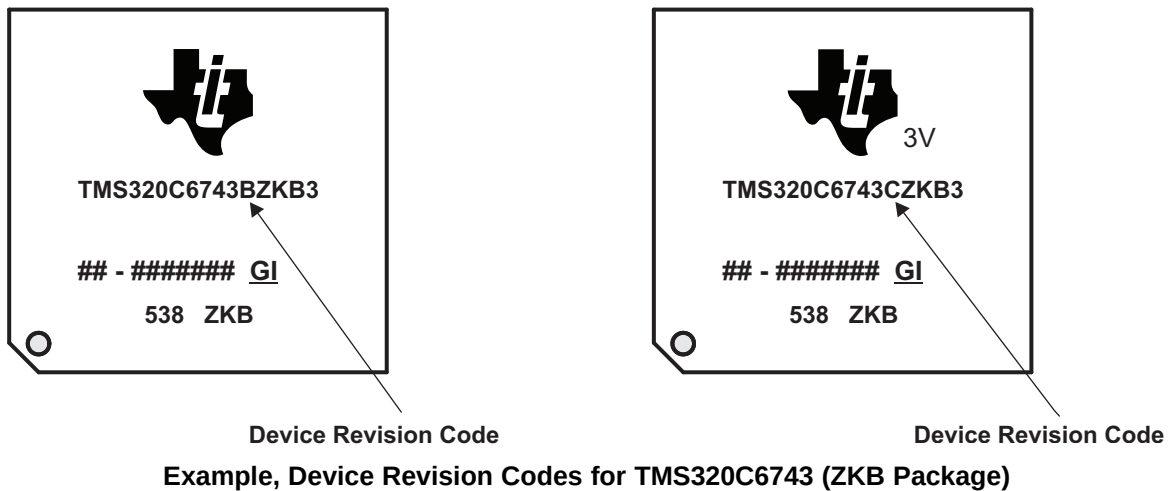


Table 1. TMS320C6743 Device Revision Codes

DEVICE REVISION CODE (xx)	SILICON REVISION	COMMENTS
D	3.0	All Silicon Revision 3.0 parts support a minimum operating DVDD (I/O) voltage of 3.0V; therefore, no additional marking is necessary.
C	2.1	Silicon Revision 2.1 parts that have a minimum operating DVDD (I/O) voltage of 3.0V can be identified by the 3V marking next to the TI logo on the package. See Example, Device Revision Codes for TMS320C6743 (ZKB Package) for details.
B	2.0	Silicon Revision 2.0 parts that have a minimum operating DVDD (I/O) voltage of 3.0V can be identified by the 3V marking next to the TI logo on the package. See Example, Device Revision Codes for TMS320C6743 (ZKB Package) for details.
A	1.1	-
(blank)	1.0	-

2 Silicon Revision 3.0 Usage Notes and Known Design Exceptions to Functional Specifications

This section describes the usage notes and advisories that apply to silicon revision 3.0 of the device.

2.1 Usage Notes for Silicon Revision 3.0

Usage notes highlight and describe particular situations where the device's behavior may not match presumed or documented behavior. This may include behaviors that affect device performance or functional correctness. These usage notes will be incorporated into future documentation updates for the device (such as the device-specific data sheet), and the behaviors they describe will not be altered in future silicon revisions.

2.1.1 McASP: Inactive Slot Usage Note

On all the silicon revisions, McASP underflow (underruns) can occur if any of the McASP serializer is configured as a transmit serializer with any of the time slot-n in XTDM register field is set to inactive and EDMA is used to do the transfers. This is independent of whether the EDMA/CPU transfers are through peripheral configuration bus or the DMA port.

If the EDMA is used to service the McASP with any of the time slot-n in XTDM register field is set to inactive, EDMA may not be triggered upon enabling serializer and hence data transfer will be stalled or if data transfer has begun with some random value and goes to underrun errors, that breaks the data transfer operation.

To ensure proper McASP (transmit) data transfer either through config or EDMA port, ensure the time slot-n in XTDM register field is set to active. For example, if a serializer is configured for transmit operation with a 5-slot TDM frame in which it is only required to transmit data in slots 0 to 2, but make sure all five slots (0 to 4) should be configured as active. The EDMA configuration and user application should account for the transfer of irrelevant data to the McASP for slots 3 and 4.

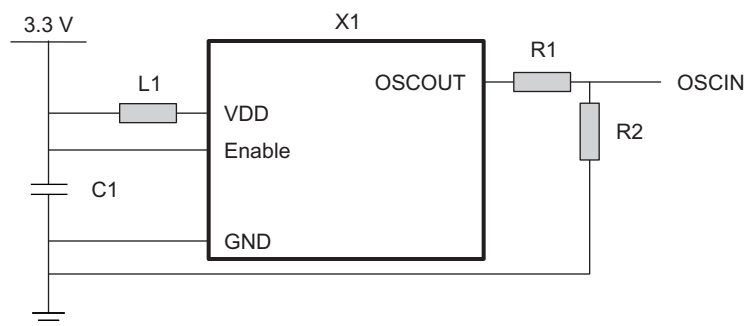
2.1.2 Clock Input Buffers Updated for Noise Immunity

For silicon revision 2.1 and later, the I/O buffers for all McASP clock inputs have been improved to provide more robust noise immunity than in previous silicon revisions. Timing specifications are not affected as a result. In particular, the specification for maximum input transition time remains the same; the improvements simply provide more margin to the existing specification.

2.1.3 System-Level ESD Immunity Usage Note

On all silicon revisions, certain design elements make this device susceptible to radiated noise during an ESD strike, as described in the standard IEC 61000-4-2. Exposure to the electrical noise caused by the ESD can cause soft device failures due to noise coupling on the system clock (OSCIN). ESD events within the IEC spec range do not cause permanent device damage and full functionality is recoverable with a device reset. The sensitivity to this noise issue is primarily due to the 1.2V oscillator/clock input implemented on this device. The low voltage range, coupled with slow rise and fall times, provides a lower noise margin than other TI devices with higher voltage internal oscillators (for example, 1.8V or 3.3V oscillators).

If ESD robustness is a concern, it is strongly recommended to avoid using the internal oscillator as a clock source. An external 3.3V clock source with a resistor voltage divider as in [Figure 1](#) can be used to externally generate the required 1.2V input clock. By using an external clock input with fast rise/fall times (less than 5 ns), the noise margin improves significantly, increasing ESD noise resistance.



Legend: L1 = ferrite bead; C1 = 0.1 uF; R1 = 165 ohm / 5%; R2 = 100 ohm / 5%

Figure 1. External 3.3V Clock Source

In addition to using an external clock source, several other board and software recommendations specific to this device can improve system-level ESD immunity:

- The OSCIN and OSCVSS (and OSCOUT, if used) should be routed as short as possible to reduce their ability to pick up EMI noise.
- Route the OSCIN signal on inner board layers where it is shield by power and ground planes.
- The processor should be provided as much power supply decoupling as is practical and placed as close to the processor as possible.
- Implement the PLL filtering circuits shown in the device datasheet.

These recommendations are in addition to standard methods for increasing system ESD immunity, such as using shielding enclosures, proper grounding and PCB stackup, and ESD protection circuitry.

2.2 Silicon Revision 3.0 Known Design Exceptions to Functional Specifications

The advisories are not enumerated in sequential order and hence some numbers may not appear in the document

Table 2. Silicon Revision 3.0 Advisory List

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Advisory 3.0.4 **DMA Access to L2 RAM Can Stall When DMA and C674x CPU Command Priorities are Equal**

Revision(s) Affected 3.0 and earlier

Details

Note: DMA refers to all non-CPU requests. This includes Internal Direct Memory Access (IDMA) requests and all other system DMA master requests via the Slave Direct Memory Access (SDMA) port.

The C674x Megamodule uses a bandwidth management (BWM) system to arbitrate between DMA and CPU requests issued to L2 RAM. See TMS320C674x DSP Megamodule Reference Guide, Literature Number - [SPRUFG5](#) for more information on the BWM. BWM arbitration grants L2 bandwidth based on programmable priorities and contention-cycle-counters. The contention-cycle-counters count the number of cycles for which the associated L2 requests are blocked by higher priority requests. When the contention-cycle-counter reaches a programmed threshold (MAXWAIT), the associated L2 request is granted a slice of L2 bandwidth. This prevents indefinite blocking of low priority requests when faced with the continuous presence of higher priority requests.

Ideally, the BWM arbitration will grant equal L2 bandwidth between equal priority DMA and CPU requests. Instead, when equal priority DMA and CPU requests arrive at the BWM, bandwidth is always granted in favor of the CPU over DMA. In the case of successive CPU requests, it is possible for the CPU to block all DMA requests until CPU traffic subsides. Additionally, some command logic in the BWM uses priority level 7, which can also result in SDMA stalls when the CPU is also programmed to priority level 7. [Figure 2](#) shows a high level diagram of the arbitration scheme used for L2 RAM requests.

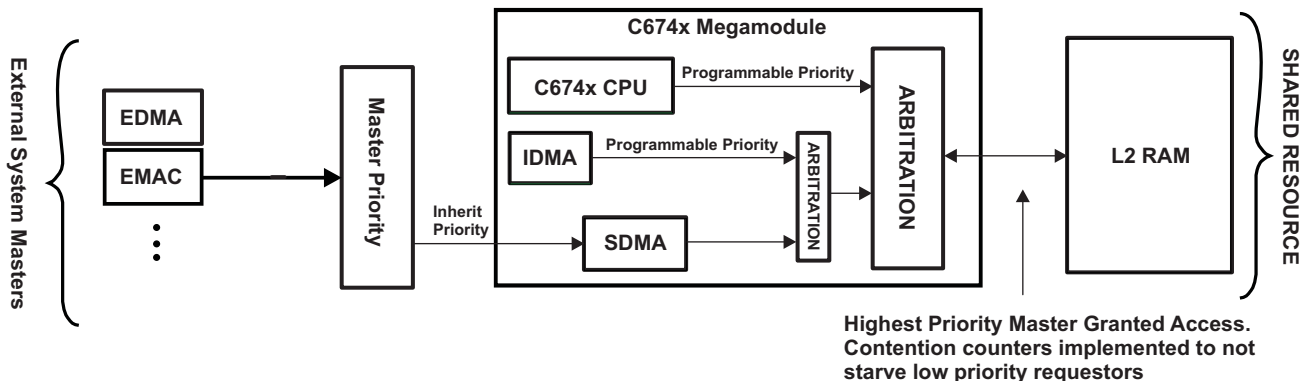


Figure 2. Priority Arbitration Scheme for L2 RAM

Workaround(s)

Configure DMA and CPU requests to different priority levels. The CPU should not be set to priority level 7. There is no penalty for setting the IDMA and SDMA priorities equal to each other.

CPU request priority is programmed within the CPUARBU register:

*/** Pseudo code only */*

```
uint32 *CPUARBU;
```

```
CPUARBU = ( uint32 * ) ( 0x01841000 );
```

```
/* Set priority different from IDMA/SDMA */
```

```
*CPUARBU = [CPU_PRIORITY];
```

IDMA request priority is programmed within the IDMA1_COUNT register

/** Pseudo code only */

```

Uint32 *IDMA1_SRC, *IDMA1_DST;
Uint32 *IDMA1_CNT;

IDMA1_SRC = ( Uint32 * ) ( 0x01820108 );
IDMA1_DST = ( Uint32 * ) ( 0x0182010C );
IDMA1_CNT = ( Uint32 * ) ( 0x01820110 );

*IDMA1_SRC = sourceAddress;
*IDMA1_DST = destinationAddress;

/* Set IDMA priority different from CPU */
*IDMA_CNT = ( [IDMA_PRI] << [IDMA_PRI_SHIFT] ) | buffSize ;

```

SDMA request priority is inherited from the MSTPRI registers

/** Pseudo code only */

```

Uint32 *MSTPRI1, *MSTPRI2;

MSTPRI1 = ( Uint32 * ) ( 0x01C14114 );
MSTPRI2 = ( Uint32 * ) ( 0x01C14118 );

/* Set SDMA master priorities different from CPU */
*MSTPRI1 = [MAST_PRI] << [MAST_SHIFT];
*MSTPRI2 = [MAST_PRI] << [MAST_SHIFT];

```


Advisory 3.0.13 *EMIFA: Asynchronous Memory Timeout Error Persistence*

Revision(s) Affected 3.0 and earlier

Details

In Extended Wait mode, during a read access to an asynchronous memory, if the WAIT input does not go inactive within maximum extended wait cycles programmed in the Async Wait Cycle Config register, the EMIFA will report a time-out error. The data returned for this access will be all zeros. If this access is followed by a read to the EMIFA's memory-mapped register (MMR) space, the EMIFA will still report a time-out error but with the correct data for the MMR read. The EMIFA will hold the time-out error until another asynchronous access without a time-out error or an SDRAM access is performed.

This issue is only applicable if all of the following are true:

- The EMIFA is used for asynchronous memory accesses in Extended Wait mode.
- There is a potential for a time-out error to occur, that is, the asynchronous memory will not de-assert the WAIT input.
- If asynchronous memory read with time-out error is followed by an MMR read.

Workaround(s)

If a time-out occurs, perform any of the following:

- A dummy read to another asynchronous memory chip select that is not configured to be in Extended Wait mode.
- A dummy read to the same asynchronous memory chip select after disabling the Extended Wait mode on that chip select.
- A dummy read to SDRAM

Advisory 3.0.14	<i>A Single CHIPINTn Interrupt Event Will Register Multiple Times in the DSP Event Combiner Module (ECM)</i>
Revision(s) Affected	3.0 and earlier
Details	The C674x DSP megamodule supports twelve maskable hardware interrupt signals (CPUINT4 through CPUINT15). Single system interrupts may be mapped directly to a CPUINTn hardware interrupt, or multiple system interrupts may be combined by the ECM into a single signal before mapping to a CPUINTn interrupt. See SPRUFG5 - TMS320C674x DSP Megamodule Reference Guide for more information on how DSP interrupts are handled. The ECM expects all incoming interrupts to be pulse interrupts, however the [SYSCFG_CHIPSIG_]CHIPINTn interrupts are level interrupts. This mismatch in interrupt types will cause a single CHIPINTn interrupt event to register multiple times in the ECM.
Workaround(s)	The CPUINTn hardware interrupts can support both pulse and level interrupts so CHIPINTn interrupts should be mapped directly to CPUINTn hardware interrupts. Furthermore, if the ECM is used for other system interrupts, the CHIPINTn interrupts should be masked out in the EVTMASKn registers.

Advisory 3.0.19 *Incorrect Masking of the C674x CSR:SAT Bit*

Revision(s) Affected 3.0 and earlier

Details

The C674x CPU supports a Saturation feature for key arithmetic operations. If an operation results in saturation, the SAT (saturation) bit in the control status register (CSR) is set. In normal operation, one or more functional units can simultaneously perform arithmetic operations that can result in saturation. In the case of simultaneous arithmetic operations, the SAT bit is set if at least one functional unit's operation results in saturation. The saturation status register (SSR) provides saturation flags for each functional unit, making it possible for the program to distinguish between saturations caused by different instructions in the same execute packet. Also, there is no direct connection to the SAT bit in the control status register (CSR); writes to the SAT bit have no effect on SSR and writes to SSR have no effect on the SAT bit.

In the case where a 2 cycle .M unit instruction is in the delay slot of a 4 cycle instruction of the same .M unit, and if both instructions are expected to generate results in the same cycle, the CSR:SAT bit will be incorrectly masked. Ideally, the CSR:SAT bit should be set if any one of the two .M unit instruction causes a saturation. Instead, the arithmetic saturation result of the 2 cycle .M unit instruction will overwrite the CSR:SAT bit.

All of the following must take place in order for an application to be affected by this advisory:

1. A 2 cycle .M unit instruction and a 4 cycle .M unit instruction are issued simultaneously
2. Both instructions are processed on the same side
3. The 2 cycle instruction is in the delay slot of the 4 cycle instruction so that the results of both instructions are generated in the same cycle
4. The saturation result of the 4 cycle .M unit instruction is different from the saturation result of the 2 cycle .M unit instruction
5. The application checks for the saturation flag and uses the saturation result of the 4 cycle instruction

Workaround(s)

Perform one of the following:

- For the location of code where saturation results are monitored, do not mix datatypes so that 2 cycle and 4 cycle .M unit instructions are not issued together.
- Do not mix floating point .M unit instruction with fixed point 2 cycle .M unit instructions.

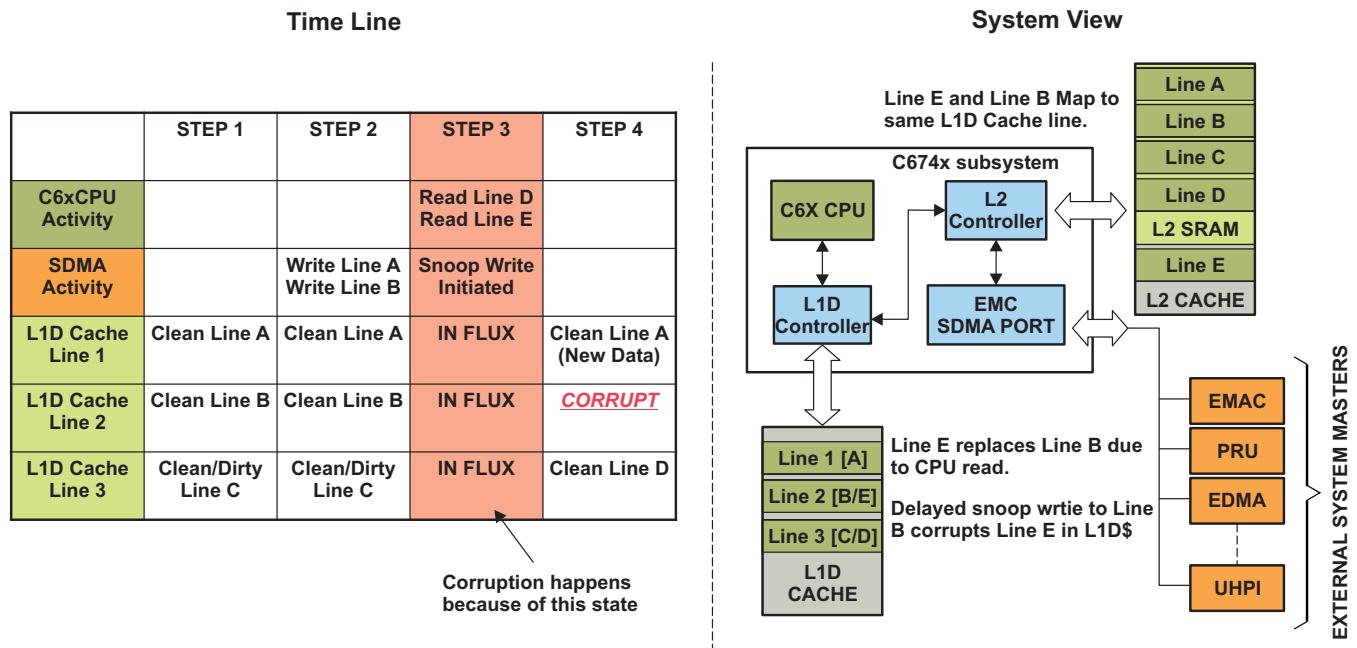


Figure 3. Example of L1D Cache Corruption

Workaround(s)

Method 1: Do not perform two CPU read operations in the same clock cycle. For C code, use compiler flag (**--c64p_dma_l1d_workaround**) available in the C6000 Compiler (CodeGen) Tools version 7.0.2 and later. For assembly code, the --c64p_dma_l1d_workaround flag will only issue a warning.

Method 2: In cases where buffer access will not be shared between CPU and SDMA, unintended CPU/SDMA cache-line sharing can be avoided by aligning CPU and SDMA buffers to 64-byte boundaries. Aligning buffers to 64-byte boundaries will result in wasted space, however it ensures that the CPU and SDMA buffers will not have partial segments which overlap into the same L1D cache line.

```

/** Pseudo code only */
Uint8 *SDMA_BUFF, *CPU_BUFF;

/* 64-byte aligned allocation Option 1 */
SDMA_BUFF = malloc( (Int32) (( SDMA_BUFF_SIZE + 63)/64) * 64 );
CPU_BUFF = malloc( (Int32) ((CPU_BUFF_SIZE + 63)/64) * 64 );

SDMA_BUFF = (Uint8 *) ( (Int32) SDMA_BUFF & ~63 );
CPU_BUFF = (Uint8 *) ( (Int32) CPU_BUFF & ~63 );

/* 64-byte aligned allocation Option 2 with BIOS Call */
SDMA_BUFF = MEM_alloc( IRAM, SDMA_BUFF_SIZE, 64 );
CPU_BUFF = MEM_alloc( IRAM, CPU_BUFF_SIZE, 64 );

```

Method 3 Manage access to a 64-byte boundary aligned buffer that is shared between CPU and SDMA by implementing a semaphore and forcing cache writeback operations if there are CPU writes. With this method, the semaphore ensures that there is clear ownership of the buffer between CPU and SDMA, and the CPU manages cache coherence by using explicit cache writeback operations.

```

/** Pseudo code only */
/* Example with EDMA as the external master */
EDMA_ISR() {
/* EDMA releases ownership of buffer */
SEM_post(SyncSemaphore);
return;
}

main() {
    while(COND) {
        /* CPU waits for ownership of buffer */
        SEM_pend(SyncSemaphore);

        /******
        /** CPU Processing **/
        /******
        /* Cache writeback for shared block */
        /* Buffer must be 64-byte aligned */
        BCACHE_wbInv( blockPtr, blockSize, WAIT );

        /* Initiate EDMA */
        EDMA_Event_Generate();
    }
}

```

Method 4 Do not allow SDMA to access L2 RAM. SDMA can use buffers in L1D RAM instead of L2 RAM.

Method 5 Configure the entire L2 RAM as cache. Critical peripheral data can be accessed in L1D RAM instead of L2 RAM.

Method 6 Configure the entire L2 RAM as normal SRAM (no cache).

Method 7 Configure the entire L1D RAM as normal SRAM (no cache).

Advisory 3.0.25	<i>USB0: CPU gets Stale Receive Data from the Data Buffer located in External Memory</i>
Revision(s) Affected	3.0 and earlier
Details	When CPPI DMA completes a receive data transaction it posts a write to the Rx data buffer located in external memory, posts a write to update the descriptor located in external memory, and raises an interrupt to CPU. When the system load is high, the posted writes to DDR may not be complete before the CPU receives the interrupt. In this case, the CPU would fetch stale receive data from the Rx data buffer located in external memory.
Workaround(s)	Initialize the datalength descriptor field to zero. CPPI DMA updates this field after the completion of an RX DMA operation with the actual number of bytes received. In the ISR (actually in a deferred call context), poll this field until it becomes a non-zero value to ensure data buffer has been updated with actual data. The descriptor buffer write is posted after the data buffer write, so waiting for the descriptor field to be updated ensures the data buffer has been updated. Since this workaround involves deferred procedure calls (whose schedule can be delayed depending on OS load), the latency sensitive application (like ISO Audio) might be affected by delay in notification to the application.

Advisory 3.0.26	<i>USB0: Early DMA Completion in DMA Receive Mode and More Than One Endpoint is Transferring Data</i>
Revision(s) Affected	3.0 and earlier
Details	The erroneous short packet status can be detected on current endpoint and XDMA closes the Rx transfer in current endpoint. When more than one endpoint have been processed, if one of the endpoints has a short packet, then the short packet status is broadcasting to all endpoints. This results in premature completion of a Rx descriptor in generic RNDIS CPPI DMA mode.
Workaround(s)	The workaround involves monitoring transfer data size before and after transferring and reconfiguring data transfer size by software if the before and after size is different. Software must keep tracking every endpoint data transferring size. When DMA completion interrupt is received, software checks size difference. If the size is not equal, software requests the remaining data.

Advisory 3.0.27 *USB0: DMA Hung up in Frequent Teardowns*

Revision(s) Affected 3.0 and earlier**Details** Teardown receive DMA is not working perfectly. This happens when a teardown is initiated by software during the endpoint is still active. Frequent teardown results in XDMA hung up situation.**Workaround(s)** Software should make sure that DMA does not get to an unknown state during teardown by disabling the DMAEN bit in the RXCSR register. After this the teardown procedure can be initiated. Software should also add 250 ms delay during teardown.

3 Silicon Revision 2.1 Usage Notes and Known Design Exceptions to Functional Specifications

This section describes the usage notes and advisories that apply to silicon revision 2.1 of the TMS320C6743.

3.1 Usage Notes for Silicon Revision 2.1

Usage notes highlight and describe particular situations where the device's behavior may not match presumed or documented behavior. This may include behaviors that affect device performance or functional correctness. These usage notes will be incorporated into future documentation updates for the device (such as the device-specific data sheet), and the behaviors they describe will not be altered in future silicon revisions.

Silicon revision 2.1 applicable usage notes have been found on a later silicon revision. For more details, see [Section 2.1 Usage Notes for Silicon Revision 3.0](#).

3.2 Silicon Revision 2.1 Known Design Exceptions to Functional Specifications

Silicon revision 2.1 applicable advisories have been found on a later silicon revision. For more details, see [Section 2.2 Silicon Revision 3.0 Known Design Exceptions to Functional Specifications](#)

Table 3. Silicon Revision 2.1 Advisory List

Title	Page
Advisory 2.1.23 — Digital I/O Buffers Age Prematurely	19

Advisory 2.1.23 *Digital I/O Buffers Age Prematurely*

Revision(s) Affected 2.1 and earlier

Details

The 3.3 V digital I/O buffers on the device exhibit accelerated aging under use conditions with heavy switching activity. As a result, the recommended Power-On Hours (POH) listed in the device-specific data manual may not apply in all cases. For examples of representative lifetimes, see [Examples of Representative Lifetimes \(Power-On Hours\)](#).

In a typical use case, the EMIFB clock pin (EMB_CLK) may be impacted due to the high switching rate and may eventually lead to SDRAM-related failures.

NOTE: The information in [Examples of Representative Lifetimes \(Power-On Hours\)](#) and [Examples of Representative Lifetimes \(Power-On Hours\)](#) is provided solely for user convenience and **does not** extend or modify the warranty provided under any terms and conditions, including TI's Standard Terms and Conditions of Sale for Semiconductor Products.

Examples of Representative Lifetimes (Power-On Hours)

NOMINAL DVDD VOLTAGE (V)	I/O SWITCHING FREQUENCY (MHz)	DPPM ⁽¹⁾ ESTIMATE	FAIL RATE (%)	LIFETIME ESTIMATES (YEARS)					PERIPHERAL
				HOURS (HRS) PER DAY OF USE					
				2 HRS	3 HRS	7 HRS	12 HRS	24 HRS	
3.30	133	1000	0.1	8.9	5.9	2.5	1.5	0.7	EMIFB
		2500	0.25	>15	11.7	5.0	2.9	1.5	
		5000	0.5	> 15	> 15	7.3	4.3	2.1	
3.30	16.94	1000	0.1	> 15	> 15	> 15	11.6	5.8	McASP
		2500	0.25	> 15	> 15	> 15	> 15	11.5	
		5000	0.5	> 15	> 15	> 15	> 15	> 15	

⁽¹⁾ Defective parts per million.

Accelerated aging of buffers depends on I/O switching frequency and I/O voltage. Prolonged high frequency switching and operating at higher voltages causes buffer performance to degrade more rapidly.

Workaround(s)

The following methods should be used to prolong the lifetime of the device.

METHOD 1

The 3.3 V output signals should only toggle when required for system functionality. The options are to tristate output buffers when not in use, or to run at the minimum frequency required for the specific application.

METHOD 2

Reduce the I/O voltage, DVDD.

Note: Do not reduce I/O voltage on devices already deployed or showing premature aging effects. To see the effects of premature aging on output signals, See the [IO Buffer Premature Aging Assessment](#) Wiki page.

[Examples of Representative Lifetimes \(Power-On Hours\)](#) depicts the subsequent performance improvements by reducing the I/O voltage.

Examples of Representative Lifetimes (Power-On Hours)

NOMINAL DVDD VOLTAGE (V)	I/O SWITCHING FREQUENCY (MHz)	DPPM ⁽¹⁾ ESTIMATE	FAIL RATE (%)	LIFETIME ESTIMATES (YEARS)					PERIPHERAL
				HOURS (HRS) PER DAY OF USE					
				2 HRS	3 HRS	7 HRS	12 HRS	24 HRS	
3.15	133	1000	0.1	> 15	> 15	7.7	4.5	2.2	EMIFB
		2500	0.25	> 15	> 15	> 15	8.8	4.4	
		5000	0.5	> 15	> 15	> 15	12.9	6.4	
3.15	16.94	1000	0.1	> 15	> 15	> 15	> 15	> 15	McASP
		2500	0.25	> 15	> 15	> 15	> 15	> 15	
		5000	0.5	> 15	> 15	> 15	> 15	> 15	

⁽¹⁾ Defective parts per million.

The Recommended Operating Conditions range for DVDD Supply Voltage, I/O, 3.3V, has been expanded to allow for a minimum voltage of 3.0V **for Silicon Revision 2.1 and 2.0 parts with the "3V" marking only** (for more details on the die symbolization and device revision codes, see [Section 1.2, Package Symbolization and Revision Identification](#)).

Recommended Operating Conditions

		MIN	NOM	MAX	UNIT
DVDD	Supply voltage, I/O, 3.3V	3.0	3.3	3.45	V

The Absolute Maximum Ratings requirement for the Input voltage ranges, V_I I/O, 3.3V (Steady State) has been modified.

Absolute Maximum Ratings Over Operating Case Temperature Range

Input voltage ranges	V_I I/O, 3.3V (Steady State)	−0.3V to DVDD + 0.350V
----------------------	-----------------------------------	------------------------

See the [IO Buffer Premature Aging Assessment](#) Wiki page for more details on the implementation of the above workarounds.

4 Silicon Revision 2.0 Usage Notes and Known Design Exceptions to Functional Specifications

This section describes the usage notes and advisories that apply to silicon revision 2.0 of the TMS320C6743.

4.1 Usage Notes for Silicon Revision 2.0

Usage notes highlight and describe particular situations where the device's behavior may not match presumed or documented behavior. This may include behaviors that affect device performance or functional correctness. These usage notes will be incorporated into future documentation updates for the device (such as the device-specific data sheet), and the behaviors they describe will not be altered in future silicon revisions.

Silicon revision 2.0 applicable usage notes have been found on a later silicon revision. For more details, see [Section 2.1 Usage Notes for Silicon Revision 3.0](#).

4.2 Silicon Revision 2.0 Known Design Exceptions to Functional Specifications

Some silicon revision 2.0 applicable advisories have been found on a later silicon revision. For more details, see

- [Section 2.2](#), *Silicon Revision 3.0 Known Design Exceptions to Functional Specifications*
- [Section 3.2](#), *Silicon Revision 2.1 Known Design Exceptions to Functional Specifications*

5 Silicon Revision 1.1 Usage Notes and Known Design Exceptions to Functional Specifications

This section describes the usage notes and advisories that apply to silicon revision 1.1 of the TMS320C6743 device .

5.1 Usage Notes for Silicon Revision 1.1

Usage notes highlight and describe particular situations where the device's behavior may not match presumed or documented behavior. This may include behaviors that affect device performance or functional correctness. These usage notes will be incorporated into future documentation updates for the device (such as the device-specific data sheet), and the behaviors they describe will not be altered in future silicon revisions.

There are no usage notes for this device.

Silicon revision 1.1 applicable usage notes have been found on a later silicon revision. For more details, see [Section 2.1, Usage Notes for Silicon Revision 3.0](#).

5.1.1 SYSCFG: Possible Race Condition When Using KICK Registers

On Silicon Revision 1.1 and earlier, when two or more threads are simultaneously accessing the SYSCFG registers, there is the potential for one thread to lock the SYSCFG registers while another thread is still accessing them. There is no hardware semaphore to prevent this from occurring.

For example, the race condition can occur in the following situation

1. Thread 1 unlocks the SYSCFG register by writing to the KICK registers
2. An interrupt occurs and Thread 2 unlocks the SYSCFG registers as well
3. Thread 2 finishes and locks the SYSCFG registers
4. Thread 1 is locked out of the SYSCFG registers and is unable to complete its task

To prevent the SYSCFG lockout race condition, the application should unlock the SYSCFG registers via the KICK registers and leave them permanently unlocked.

Starting with silicon revision 2.0, the KICK registers will be disabled and the SYSCFG registers will be permanently accessible. Writes to the disabled KICK registers will have no effect.

5.2 Silicon Revision 1.1 Known Design Exceptions to Functional Specifications

Some silicon revision 1.1 applicable advisories have been found on a later silicon revision. For more details, see

- [Section 2.2, Silicon Revision 3.0 Known Design Exceptions to Functional Specifications](#)
- [Section 3.2, Silicon Revision 2.1 Known Design Exceptions to Functional Specifications](#)
- [Section 4.2, Silicon Revision 2.0 Known Design Exceptions to Functional Specifications](#)

Table 4. Silicon Revision 1.1 Advisory List

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Advisory 1.1.3 — SPI: Internally Generated SPI Clock Is Not 50% Duty Cycle	24
Advisory 1.1.5 — Under Specific Conditions, SDMA Activity Can Corrupt the L1D Cache and L2 RAM	25

Advisory 1.1.10 — EMIFB: AC Timings Differ From Data Manual Specifications	27
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Advisory 1.1.16 — Vil on 3.3V LVCMOS Input Buffers	29
Advisory 1.1.17 — DSP SDMA/IDMA: Unexpected Stalling and Potential Deadlock Condition	30

Advisory 1.1.3 *SPI: Internally Generated SPI Clock Is Not 50% Duty Cycle*

Revision(s) Affected 1.1 and earlier

Details When the SPI is in master mode, the generated SPICLK signal is derived from the internal SPI module clock. This SPICLK signal duty cycle is not 50% when the SPIFMTn.PRESCALE is set to an even number.

With an even prescale value, the falling edge of the SPICLK is delayed 1-2 ns regardless of the SPICLK frequency. Therefore, the high side is wider than the low side.

Workaround(s) Use the SPIFMTn.PRESCALE with an odd value if possible.

Advisory 1.1.5 Under Specific Conditions, SDMA Activity Can Corrupt the L1D Cache and L2 RAM

Revision(s) Affected 1.1 and earlier

Details

Note: DMA refers to all non-CPU requests. SDMA refers to external system DMA master requests handled via the Slave Direct Memory Access port.

The C674x Megamodule uses a two-way set associative cache for L1D. This means that every physical memory location in the system has two possible set/way locations in the cache where it can reside. See TMS320C674x DSP Megamodule Reference Guide, Literature Number - [SPRUFG5](#) for more information on the L1D cache architecture. Updated (dirty) values in L1D cache are not written back to external memory until cache activity evicts a cache-line (victim write-back) or a write-back is requested by the application.

An L1D cache-line corruption event occurs when all of the following conditions are met:

1. L1D cache evicts a dirty line (Line A) while allocating a new line (Line B) in the same set/way (cache Lines A and B consist of 64-bytes each). In order for this to happen, the following will have taken place:
 - (a) Line A was previously read by CPU because L1D is a read-allocate cache,
 - (b) Line A is dirty because its value was modified by CPU, and
 - (c) Line B is read by CPU
2. Both Line A and Line B are associated with L2 RAM, and
3. While the original L1D victim write-back from condition (1) is in progress, the SDMA performs both:
 - (a) a read or write operation to Line A in L2 RAM and
 - (b) a write operation to Line B in L2 RAM.

If all of the above conditions are met, the L2 RAM data associated with the Line A victim writeback will become corrupt. Additionally, the Line B data originating from the SDMA write will also become corrupt in L1D cache. [Figure 4](#) shows an example scenario of L1D cache and L2 RAM corruption.

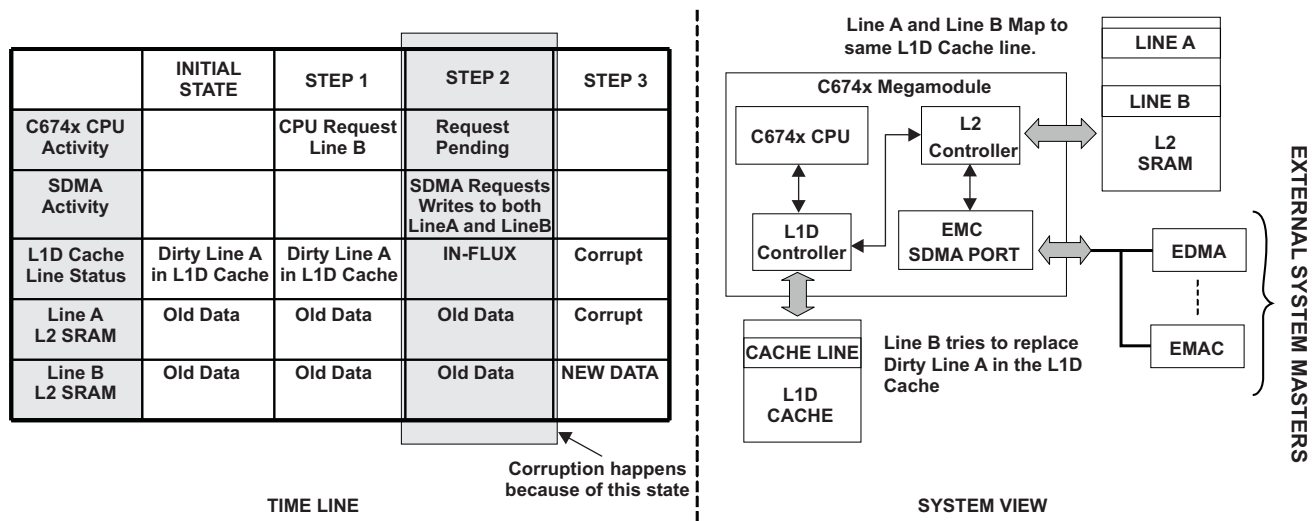


Figure 4. Example of L1D Cache and L2 RAM Corruption

Workaround(s)
Method 1

In cases where buffer access will not be shared between CPU and SDMA, unintended CPU/SDMA cache-line sharing can be avoided by aligning CPU and SDMA buffers to 64-byte boundaries. Aligning buffers to 64-byte boundaries will result in wasted space, however it ensures that the CPU and SDMA buffers will not have partial segments which overlap into the same L1D cache line.

```
/** Pseudo code only */
```

```

    Uint8 *SDMA_BUFF, *CPU_BUFF;

    /* 64-byte aligned allocation Option 1 */
    SDMA_BUFF = malloc( (Int32) (( SDMA_BUFF_SIZE + 63)/64) * 64 );
    CPU_BUFF = malloc( (Int32) ((CPU_BUFF_SIZE + 63)/64) * 64 );

    SDMA_BUFF = (Uint8 *) ( (Int32) SDMA_BUFF & ~63 );
    CPU_BUFF = (Uint8 *) ( (Int32) CPU_BUFF & ~63 );

    /* 64-byte aligned allocation Option 2 with BIOS Call */
    SDMA_BUFF = MEM_alloc( IRAM, SDMA_BUFF_SIZE, 64 );
    CPU_BUFF = MEM_alloc( IRAM, CPU_BUFF_SIZE, 64 );

```

Method 2

Manage access to a 64-byte boundary aligned buffer that is shared between CPU and SDMA by implementing a semaphore and forcing cache writeback operations after CPU writes. With this method, the semaphore ensures that there is clear ownership of the buffer between CPU and SDMA, and the CPU manages cache coherence by using explicit cache writeback operations.

```
/** Pseudo code only */
```

```

    /* Example with EDMA as the external master */
    EDMA_ISR() {
        /* EDMA releases ownership of buffer */
        SEM_post(SyncSemaphore);
        return;
    }

    main() {
        while(COND) {
            /* CPU waits for ownership of buffer */
            SEM_pend(SyncSemaphore);

            /******
            *** CPU Processing ***
            *****/

            /* Cache writeback for shared block */
            /* Buffer must be 64-byte aligned */
            BCACHE_wbInv( blockPtr, blockSize, WAIT );

            /* Initiate EDMA */
            EDMA_Event_Generate();
        }
    }

```

Method 3

Configure the entire L2 RAM as cache. Critical peripheral data can be accessed in L1D RAM instead of L2 RAM.

Method 4

Do not allow SDMA to access L2 RAM. SDMA can use buffers in L1D RAM instead of L2 RAM.

Method 5

Do not configure L1D memory as cache - use the entire address space as RAM.

Advisory 1.1.10 *EMIFB: AC Timings Differ From Data Manual Specifications*

Revision(s) Affected 1.1 and earlier

Details The timing parameters in [Table 5](#) differ from those specified in the *TMS320C6743 Fixed/Floating-Point Digital Signal Processor* data manual (literature number [SPRS565](#) or later). [Table 5](#) lists the AC timing parameters that should be used on silicon revision 1.1 and earlier.

Workaround(s) During PCB board design and layout, the AC timings specified in [Table 5](#) should be considered when designing interfaces to the EMIFB.

Table 5. Timing requirements Over Recommended Operating Conditions

NO.	PARAMETER		MIN	MAX	UNIT
19	$t_{su(DV-CLKH)}$	Input setup time, read data valid on EMB_D[15 :0] before EMB_CLK rising	1.26		ns

Advisory 1.1.11 *Electrostatic Discharge Charged-Device Model Performance*

Revision(s) Affected 1.1 and earlier**Details** The ESD to Charge Device model (CDM) is rated as passing the 300V level instead of the 500V level. The OSCOUT pin passed 300V testing but failed starting at 400V. The RSV2 pin had marginality to 500V. All of the other pins are rated as passing the 500V level.

Advisory 1.1.16	<i>Vil on 3.3V LVCMOS Input Buffers</i>
Revision(s) Affected	1.1 and earlier
Details	The input buffers on the device have shown timing sensitivity to the logic-low input voltage that can cause changes to the AC input timings. Due to this issue, input voltages must be driven at or below 0.4V to limit impact on AC timings. The timing effect on the input buffers is dependent on the Vil level: • Case 1: For signals driven with Vil <= 0.2V, the input timings will be unaffected. • For signals driven with 0.2V < Vil <= 0.4V, there may be as much as 0.5 ns degradation to input timings. This issue applies only to 3.3V LVCMOS inputs or IOs used as inputs. Signals operated at 1.8V are not affected.
Workaround(s)	Although there is no specific workaround, the following recommendations can be used to help prevent this issue: • Minimize loads as much as possible, especially DC loads that could cause the Vil to rise. Point-to-point (single-load) connections are unlikely to be affected. • Falling edges should transition as rapidly as possible (so the signal passes through the 0.2V point as early as possible). Heavily loaded nodes resulting in degraded fall times may require drivers to provide rapid input edges.

Advisory 1.1.17 **DSP SDMA/IDMA: Unexpected Stalling and Potential Deadlock Condition**

Revision(s) Affected 1.1 and earlier

Details

Note: This advisory is not applicable if DSP L2 memory is configured as 100% cache or L2 RAM is not accessed by IDMA or SDMA during run-time.

The C674x Megamodule has a Master Direct Memory Access (MDMA) bus interface and a Slave Direct Memory Access (SDMA) bus interface. The MDMA interface provides DSP access to resources outside the C674x Megamodule.

The MDMA interface is typically used for CPU/cache accesses to memory beyond the Level 2 (L2) memory level. These accesses include cache line allocates, write-backs, and non-cacheable loads and stores to/from system memories. The cacheable memories external to the C674x Megamodule are listed in [Table 6](#).

Table 6. Cacheable External Memory Resources

External Memory	Address Range
EMIFA	0x4000 0000 – 0x67FF FFFF
EMIFB	0xC000 0000 – 0xCFFF FFFF

The SDMA interface allows other DMA master peripherals (listed in [Table 7](#)) to access Level 1 Data (L1D), Level 1 Program (L1P), and L2 RAM DSP memories.

Table 7. DMA Master Peripherals

Peripheral	Group
EDMA TC0 RD	A
EDMA TC0 WR	B
EDMA TC1 RD	C
EDMA TC1 WR	D
EMAC	E

The C674x Megamodule has an L1D cache and L2 cache both implementing write-back data caches— it keeps updated values for external memory in cache for as long as possible. It writes these updated values, called "victims", to external memory when it needs to make room for new data or when requested to do so by the application. The L1D sends its victims to L2. The caching architecture has pipelining, meaning multiple requests could be pending between L1, L2, and MDMA. For more details on the C674x Megamodule and its MDMA and SDMA ports, see the TMS320C674x Megamodule Reference Guide (literature number [SPRUFG5](#)).

Ideally, the MDMA (dashed-dotted line in [Figure 5](#)) and SDMA/IDMA paths (dashed lines in [Figure 5](#)) operate independently with minimal interference. Normally MDMA accesses may stall for extended periods of time due to expected system level delays (for example, bandwidth limitations). However, when using L2 as RAM, SDMA and IDMA accesses to L2/L1 may experience unexpected stalling in addition to the normal stalls seen by the MDMA interface. For latency-sensitive traffic, the SDMA stall can result in missing real-time deadlines. In a more severe case, the SDMA stall can produce a deadlock condition in the device. An IDMA stall cannot produce a deadlock condition.

Note: SDMA/IDMA accesses to L1P/D will not experience an unexpected stall if there are no SDMA/IDMA accesses to L2. Unexpected SDMA/IDMA stalls to L1 happen only when they are pipelined behind L2 accesses. Additionally, the deadlock scenario will be avoided if there are no SDMA accesses to L2.

Figure 5 is provided for illustrative purposes and is incomplete because of simplification. The IDMA/SDMA (dashed-lines) path could also go to L1D/L1P memories, and IDMA can go to DSP CFG peripherals. MDMA transactions can originate also from L1P or L1D through the L2 controller or directly from DSP.

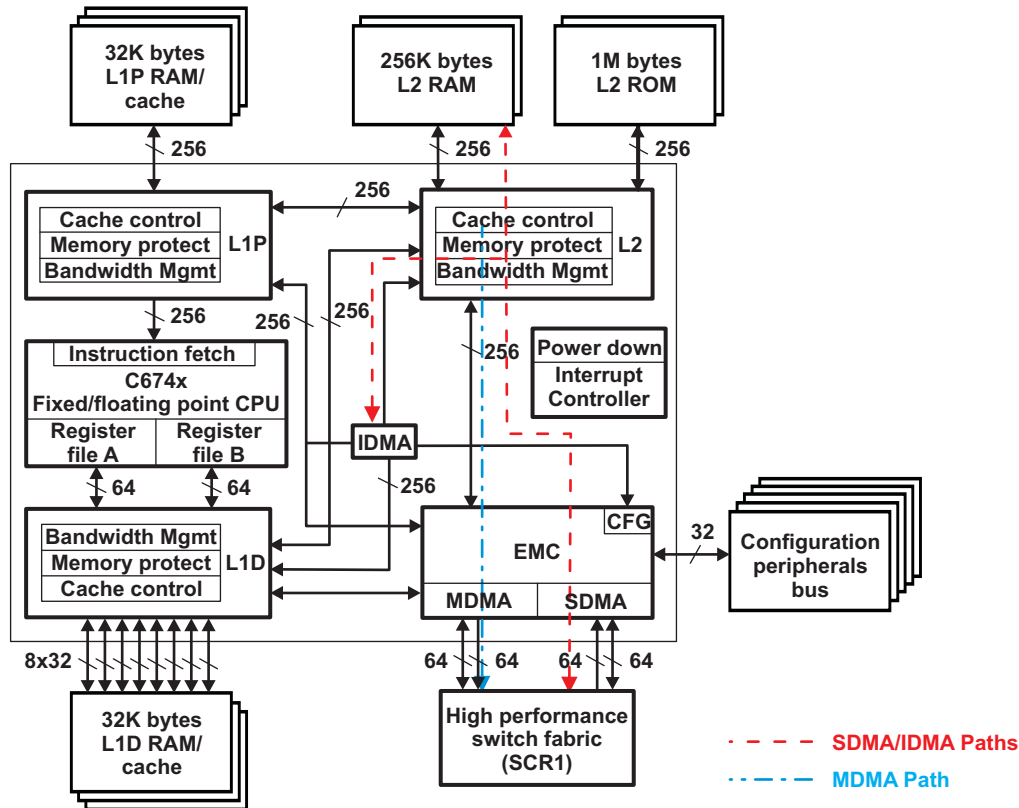


Figure 5. C674x Megamodule

The duration of the SDMA/IDMA stalls depend on the quantity/characteristics of the L1/L2 cache and the MDMA traffic in the system. Therefore, it is difficult to predict if stalling will occur and for how long.

IDMA/SDMA stalling and any system impact is most likely in systems with excessive context switching, L1/L2 cache miss/victim traffic, and heavy access to external memory.

Use the following procedure to determine if SDMA/IDMA stalling is the cause of real-time deadline misses for existing applications. Situations where real-time deadlines may be missed include loss of McASP samples and poor peripheral throughput.

1. Determine if the transfer that is missing the real-time deadline is accessing L2 or L1D memory. If not, then SDMA/IDMA stalling is not the source of the real-time deadline miss.
2. Identify all SDMA transfers to/from L2 memory (for example, EDMA transfer to/from L2 from/to a UART, HPI block transfer to/from L2). If there are no SDMA transfers to/from L2, then SDMA/IDMA stalling is not the source of the problem.

3. Redirect all SDMA transfers to L2 memory to other memories using one of the following methods:
 - (a) Temporarily transfer all the L2 SDMA transfers to L1D SRAM.
 - (b) If not all L2 SDMA transfers can be moved to L1D memory, temporarily direct some of the transfers to memory in Table 1 and keep the rest in L1D memory. There should be no L2 SDMA transfers.

If real-time deadline misses are solved using any of the options in Step 3, then IDMA/SDMA stalling is likely the source of the problem.

A deadlock situation may arise if the following sequence of events occurs:

Step 1: A DMA master from any group (listed in Table 7) issues a write command to the DSP's SDMA, and a DMA master from the same group issues a subsequent write command to cacheable memory outside of the C674x Megamodule (listed in Table 1). All write commands pass through Switched Central Resource 1 (SCR1). For more details on SCRs, see the device Technical Reference Manual [SPRUH90](#).

Step 2: The DSP's SDMA asserts itself as not ready and is unable to accept the write data from Step 1, and a cache line writeback is initiated from DSP memory to the same cacheable memory from Step 1. The cache line writeback command also passes through SCR1.

With the above scenario, it is possible for SCR1 to order the write commands from Step 1 in front of the write commands from Step 2. Due to the MDMA/SDMA blocking behavior, the SDMA commands from Step 2 will be waiting for the MDMA traffic from Step 1 to finish, resulting in a deadlock situation at SCR1. Figure 6 is provided for illustrative purposes and is incomplete because of simplification.

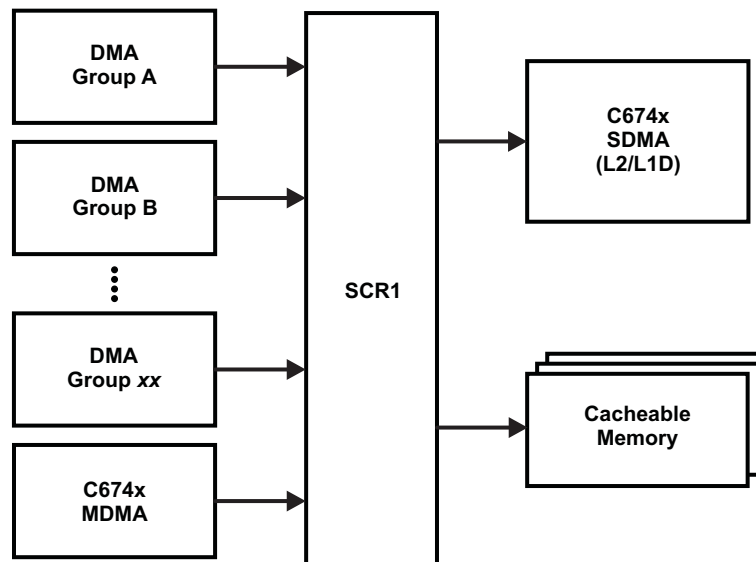


Figure 6. SCR1 System Interconnect

Workaround(s)

Entirely eliminate IDMA/SDMA stalling and potential for a deadlock condition using one of the following two methods:

1. Configure the entire L2 RAM as 100% cache (for example, move all data buffers from L2 to L1D or other memory). Note: Some throughput degradation is expected when the buffers are moved out to external memo
2. Eliminate all IDMA/SDMA access to L2 RAM when IDMA/SDMA stalling would have an impact by performing one of the following:
 - (a) Constrain each DMA master group to perform writes to either DSP memory space or external memory space, but not to both, or

- (b) Force each DMA master group to complete pending write commands to either DSP memory space or cacheable memory space before initiating writes to a different destination. Pending write commands from DMA masters are forced to complete when the DMA master initiates a read from the same destination memory. Note that in the case of off-chip memory, a read command only forces the completion of write commands within a 2KB-aligned window.

6 Silicon Revision 1.0 Usage Notes and Known Design Exceptions to Functional Specifications

This section describes the usage notes and advisories that apply to silicon revision 1.0 of the TMS320C6743 device.

6.1 Usage Notes for Silicon Revision 1.0

Usage notes highlight and describe particular situations where the device's behavior may not match presumed or documented behavior. This may include behaviors that affect device performance or functional correctness. These usage notes will be incorporated into future documentation updates for the device (such as the device-specific data sheet), and the behaviors they describe will not be altered in future silicon revisions.

Silicon revision 1.0 applicable usage notes have been found on a later silicon revision. For more details, see [Section 4.1, Usage Notes for Silicon Revision 3.0](#) and see [Section 5.1, Usage Notes for Silicon Revision 1.1](#).

6.2 Silicon Revision 1.0 Known Design Exceptions to Functional Specifications

Some silicon revision 1.0 applicable advisories have been found on a later silicon revision. For more details, see

- [Section 2.2, Silicon Revision 3.0 Known Design Exceptions to Functional Specifications](#)
- [Section 3.2, Silicon Revision 2.1 Known Design Exceptions to Functional Specifications](#)
- [Section 4.2, Silicon Revision 2.0 Known Design Exceptions to Functional Specifications](#)
- [Section 5.2, Silicon Revision 1.1 Known Design Exceptions to Functional Specifications](#)

Table 8. Silicon Revision 1.0 Advisory List

Title	Page
Advisory 1.0.12 — SPI Communication Failure for Data Receipt	35

Advisory 1.0.12
SPI Communication Failure for Data Receipt
Revision(s) Affected

1.0

Details

There is a potential SPI communication failure on data receipt. When the communication failure occurs, the data received in the SPIBUF register is not correct. The data error pattern is not consistent between failures. The failure impacts both master and slave mode.

This issue is caused by un-matched delays between the clock and data paths of the shift register. The non-matched delays cause the clock edge to be detected earlier than the appropriate data. This results in inconsistent/incorrect receive data being copied into the SPIBUF register.

Workaround(s)

There is no recommended workaround.

Adjusting the following settings may allow you to find a working region:

- Adjust the SPI settings of prescale, phase, and polarity
- Increase the core VDD to a range between 1.25V and 1.32V
- Decrease the CPU operating frequency

Increasing the core VDD or slowing down the CPU operating frequency is ideal to work across a variety of conditions. Although the adjustments recommended above may be used to find a working setup and allow further development to take place, these adjustments cannot be guaranteed to alleviate the issue across devices, hardware platforms, and temperature.

Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

This silicon errata revision history highlights the technical changes made to SPRZ296F revision to make it SPRZ296G revision.

Scope: Applicable updates relating to the device have been incorporated. Added Silicon Revision 3.0 device-specific information.

Revision History

SEE	ADDITIONS/MODIFICATIONS/DELETIONS
Section 2.1	Added the following new usage note to Usage Notes for Silicon Revision 3.0: Section 2.1.1, McASP: Inactive Slot Usage Note
Section 2.2	Added the following new advisories to Silicon Revision 3.0 Known Design Exceptions to Functional Specifications: Advisory 3.0.25, USB0: CPU gets Stale Receive Data from the Data Buffer located in External Memory Advisory 3.0.26, USB0: Early DMA Completion in DMA Receive Mode and More Than One Endpoint is Transferring Data Advisory 3.0.27, USB0: DMA Hung up in Frequent Teardowns
Section 5.2	Updated/Changed Advisory 1.1.17 text from "...System Reference Guide SPRUFK9" to "...Technical Reference Manual SPRUH90"

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